

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150310002

Qualification of Vanguard Facility as an additional FAB site source for select OPA2364xx devices in the 0.60UM Process
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team SC Business Services

PCN# 20150310002 Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number: PCN20150310002 PCN Date: 03/13/20							: 03/13/2015				
Title: Qualification of Vanguard Facility as an additional FAB site source for selected devices in the 0.60UM process											
Customer Contact: PC				PCN	N Manager		pt:		Quality Services		
*Proposed 1 st Ship Date: 06/				6/13/2015	015 Estimated Sample Av				Date provided at sample request		
Change Type:											
Assembly Site					Assembly P					Assembly Materials	
	Des			Electrical Speci						nical Specification	
\sqcup		Site					ng/Labeling	<u> </u>	Test Process		
		er Bump Site			Wafer Bum		<u> </u>		Bump Process		
	Waf	er Fab Site			Wafer Fab I			Wafer I	ab Process		
		Part number c									
					PC	<u> </u>	<u>Details</u>				
Desc	ripti	on of Chang	je:								
Texas Instruments is pleased to announce the qualification of its Vanguard fabrication facility as an additional wafer FAB source for the selected devices listed in "Product Affected" section. Currently Qualified Sites, Process, wafer dia. Additional Site, Process, wafer dia.											
		F2, 0.60UM, 2			ess, water ui	a.	Additional Site, Process, wafer dia. Vanguard, VIS 0.6UM DPDM, 200mm				
The 0.6um DPDM process has been running in production successfully in Vanguard since 2006. Qualification details are provided in the Qual Data Section.											
Reas	Reason for Change:										
Continuity of Supply											
Antic	ipat	ed impact o	n Fo	rm,	Fit, Function	on,	Quality or Reliabi	lity	(positive	e / negative):	
None											
Changes to product identification resulting from this PCN:											
Current											
Chip Site C			Ch	Chip site code (20L)			Chip country code (2	21L)			
TSMC-WF2				TS2			TWN				
New											
· · · · · · · · · · · · · · · · · · ·		Ch	Chip site code (20L)			Chip country code (21L)					
Vanguard (VIS) VAN				TWN							
Sample product shipping label (not actual product label)											
TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: LBL: 5A (L) T0: 1750 (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0: USA (22L) ASO: MLA (23L) ASO: MYS											

Product Affected:						
OPA2364AID	OPA2364AIDGKT	OPA2364ID	OPA2364IDGKTG4			
OPA2364AIDG4	OPA2364AIDGKTG4	OPA2364IDGKR	OPA2364IDR			
OPA2364AIDGKR	OPA2364AIDR	OPA2364IDGKRG4	OPA2364IDRG4			
OPA2364AIDGKRG4	OPA2364AIDRG4	OPA2364IDGKT				

Qualification Report

OPA2364 Vanguard (aka VIS FAB - qualified process flow 0.5um/0.6um) model transfer from TSMC FAB2 Approved 01/23/2015

		Qual Device:	QBS Process:	QBS Process:	QBS Process:
Attributes Assembly Site		OPA2364AIDGK ASE SHANGHAI	DDC112Y CRS	OPA343U OSE	TSC2046IPW
Assembly Site		ASL SHANGHAI	ONS	OSL	IAI
Package Family		VSSOP	TQFP	SOIC	TSSOP
Flammability Rating		UL 94 V-0	UL94 Class V-0	UL94 Class V-0	UL94 Class V-0
Wafer Fab Site		VANGUARD-8 VANGUARD VAN		VANGUARD	VANGUARD
Wafer Fab Process		0.6/0.5um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM
Test Name / Condition	Duration	Qual Device: OPA2364AIDGK	QBS Process: DDC112Y	QBS Process: OPA343U	QBS Process: TSC2046IPW
Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	1/77/0
Autoclave 121C	96 Hours	-	1/77/0	1/77/0	1/77/0
Temperature Cycle, - 65/150C	500 Cycles	3/231/0	1/77/0	1/77/0	1/77/0
High Temp. Storage Bake, 150C	1000 Hours	-	1/77/0	-	-
High Temp. Storage Bake, 170C	420 Hours	-	-	-	1/77/0
Thermal Shock -65/150C	500 Cycles	-	1/77/0	-	1/77/0
Life Test, 125C	1000 Hours	-	-	-	-
Life Test, 150C	300 Hours	3/231/0	1/77/0	1/77/0	1/77/0
ESD - HBM	2500 V	2/6/2000	-	-	-
ESD - CDM	1000 V	3/9/2000	1/3/2000	-	1/3/2000
Latch-up (per JESD78)		3/18/2000	1/6/2000	1/6/2000	1/6/2000
Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com